Foreword

Since July 2006, following the European Union (EU)'s Restriction of Hazardous Substances (RoHS) legislation, the consumer electronics industry has offered "green" products by eliminating Pb-containing solders and other toxic materials. This trend is continuing in other industries such as automobiles, telecommunication, high-end computers, space, and military applications. Technical symposiums on "Pb-free Solders" sponsored by TMS and organized by the Electronic Packaging and Interconnections Materials Committee for the past 15 years have been playing a key role in this transition.

The 2009 Pb-free Solders Symposium was held from February 15 to 19, 2009, at the TMS Annual Meeting in San Francisco, CA, USA. One hundred twenty papers were presented in eight sessions including 26 poster papers. This is the largest number of papers presented on Pb-free solders in one technical symposium. Reliability issues related to Pb-free solder joints such as electromigration, Sn whiskers, interfacial reactions, and thermal fatigue were the major topics of discussion.

Many authors who participated in the symposium submitted manuscripts for this special issue on Pb-free solders. After rigorous peer review and careful manuscript revision, the papers in this special issue were finally accepted for publication. We appreciate the diligent work of all authors and reviewers for making this special issue possible. Special thanks also go to Prof. Suzanne Mohny, editor of the *Journal of Electronic Materials*, for her assistance in the review and publication process.

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